

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: COOK, et al

Serial No: 10/035659

Filed: 10/26/2001

For: DIRECT BONDING OF GLASS
ARTICLES FOR DRAWING

Examiner: John Hoffman

Group Art Unit: 1731

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. §§ 1.56, 1.97 – 1.98Commissioner of Patents
Alexandria, VA 22313-1450

Dear Sir:

The Examiner's attention is hereby directed to the following reference(s) listed on the attached Form PTO-1449 for consideration in connection with the examination of the above-identified patent application. One copy of the reference(s) is enclosed, except any US Patents.

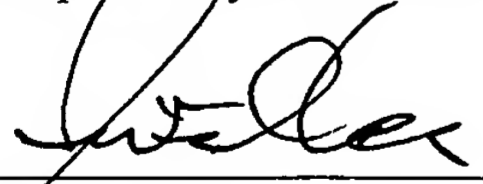
This submission does not represent that a search has been made or that no better art exists and does not constitute an admission that each or all of the enclosed documents constitute "prior art." If it should be determined that any of the submitted documents do not constitute "prior art" under United States law, applicant(s) reserve the right to present to the office the relevant facts and law regarding the appropriate status of such documents.

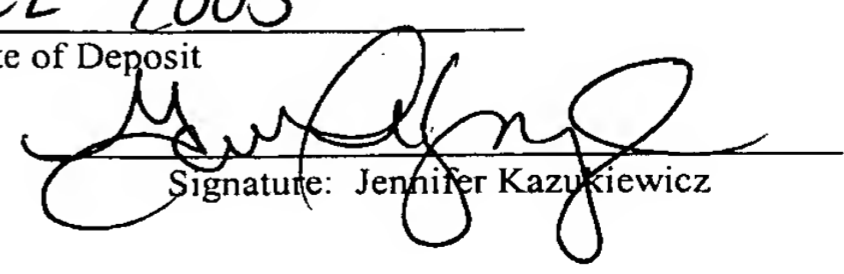
Applicant(s) further reserve the right to take appropriate action to establish the patentability of the disclosed invention over the enclosed references, should one or more of the references be applied against the claims of the present application.

The undersigned attorney is granted limited recognition by the Office of Discipline and Enrollment of the USPTO to practice before the USPTO in capacity as an employee of Corning Incorporated. A copy of the document granting such limited recognition either has been previously submitted or is submitted herewith for the record.

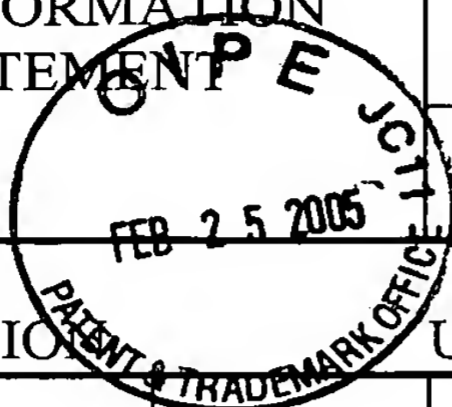
Please direct any questions or comments to the undersigned at (607) 248-1253.

Respectfully submitted,


Siwen Chen
Corning Incorporated
SP-TI-03-1
Corning, NY 14831
607-248-1253
Date: February 22, 2005

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Commissioner of Patents, Alexandria, VA 22313-1450 on	
<u>2-22-2005</u>	
Date of Deposit	
	
Signature: Jennifer Kazukiewicz	

FORM PTO-1449 (MODIFIED) LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS INFORMATION DISCLOSURE STATEMENT	ATTORNEY DOCKET NO.	SERIAL NO.
	SP01-302	10/035659
	APPLICANT: COOK, et al.	
	FILING DATE 10/26/2001	GROUP: 1731



REFERENCE DESIGNATION			U.S. PATENT DOCUMENTS				
Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
	AA	4,186,999	2/5/80	Harwood et al	350	96.21	
	AB	4,530,452	7/23/85	Balyasny et al	225	96	
	AC	4,626,068	12/2/86	Caldwell	350	96.34	
	AD	5,183,710	2/2/93	Gerbino	428	405	
	AE	5,346,583	9/13/94	Basavanhally	156	629	
	AF	5,451,547	9/19/95	Himi et al	437	225	
	AG	5,452,122	9/19/95	Tsuneda et al	359	281	
	AH	5,579,421	11/26/96	Duvall et al	385	14	
	AI	5,631,986	5/20/97	Frey et al	385	78	
	AJ	5,846,638	12/8/98	Meissner	428	220	
	AK	5,852,622	12/22/98	Meissner et al	372	39	
	AL	5,989,372	11/23/99	Momoda et al	156	89.11	
	AM	6,030,883	2/29/00	Nishimoto et al	438	455	
	AN	6,048,103	4/11/00	Furukata et al	385	73	
	AO	6,249,619	6/19/01	Bergmann et al	385	11	
	AP	6,275,336	8/14/01	Yoshikawa et al	359	484	
	AQ	6,359,733	3/19/02	Iwatsuka et al	359	500	
	AR	6,583,029	6/24/03	Abe et al	438	455	
	AS	2002/0108556	8/15/02	Ebbers	117	2	
	AT	2003/0079503	5/1/03	Cook et al	65	407	
	AU	2003/0079823	5/1/03	Sabia	156	99	
	AV	2003/0081906	5/1/03	Filhaber et al	385	60	
	AW	2003/0206345	11/6/03	Sabia et al	359	484	
	AX	2003/0206347	11/6/03	Sabia et al	359	484	
	AY	2003/0081930	5/1/03	Filhaber et al	385	147	
	AZ	4,960,331	10/2/90	Goldman et al	356	350	
	BA	5,319,483	6/7/94	Krasinski et al	359	113	
	BB	5,441,803	8/15/95	Meissner	428	220	
	BC	5,689,519	11/18/97	Fermann et al	372	18	
	BD	6,120,917	9/19/00	Eda	428	692	
	BE	6,548,176	4/15/03	Gwo	428	420	
	BF	6,621,630	9/16/03	Iwatsuka	359	484	
	BG	5,915,193	6/22/99	Tong et al.	438	455	
	BH	5,785,874	7/28/98	Eda	216	24	
	BI	5,932,048	8/3/99	Furukawa et al.	156	153	
	BJ	6,129,854	10/10/00	Ramsey et al.	216	18	
	BK	6,153,495	11/28/00	Kub et al.	438	459	
	BL	6,178,779	1/30/01	Drouart et al.	65	391	

	BM	6,098,429	8/8/01	Mazabraud et al.	65	392	
	PBN	4,407,667	10/4/83	LeNoane et al.	65	3.11	

FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Sub-Class	Translation Yes No
BO	WO01/98225	12/27/01	PCT	C03C	27/06	
BP	WO00/17698	3/30/00	PCT	G02F	1/09	
BQ	DE19731075	1/21/99	Germany (English Abstract)	C03C	29/00	
BR	DE2130905	1/11/73	Germany (English Abstract)	H01J	19/56	
BS	08-146351	6/7/96	Japan (English Abstract)	G02B	27/28	
BT	2002321947	4/25/01	Japan (English Abstract)	C03C	27/00	
BU	03-115178	5/16/91	Japan (English Abstract)	C04B	37/00	
BV	52-78450	7/1/77	Japan (English Abstract)	C03B	37/00	
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OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

BX	ONISHI et al., "A novel temperature compensation method for SAW devices using direct bonding Techniques," <i>Ultrasonics Symp</i> , 1997, IEEE Proceedings, 5-8 Oct, 1997 Pages 227-230.
BY	Arthur Landrock; "Surface Preparation of Adherends"; Adhesives Technology Handbook; 1985; page 117-118
BZ	A. Sayah, D. Solignac, T. Cueni, M.A.M. Gijis, "Development of novel low temperature bonding technologies for microchip chemical analysis applications," Sensors and Actuators, 84 August (2000) pp. 103-108.
CA	P. Rangsten, O. Vallin, K. Hermansson, Y. Backlund, "Quartz-to-Quartz Direct Bonding," Journal of the Electrochemical Society, V. 146, N. 3, pp. 1104-1105, (1999).
CB	H. Nakanishi, T. Nishimoto, M. Kanai, T. Saitoh, R. Nakamura, T. Yoshida, S. Shoji, "Condition optimization, reliability evaluation of SiO ₂ -SiO ₂ HF bonding and its application for UV detection micro flow cell," Sensors and Actuators, V. 83, pp. 136-141, May 2000.
CC	A. Yamada, T. Kawasaki, M. Kawashima, "Bonding Silicon wafer to Silicon Nitride With Spin-on Glass as Adhesive," Electronics Letters, March 26, 1987, Vol. 23, No. 7 Pages 314-315.
CD	D.J. Harrison, Karl Fluri, Kurt Seiler, Zhonghui Fan, Carlo S. Effenhauser, Andreas Manz, "Micromachining a Miniaturized Capillary Electrophoresis-Based Chemical Analysis System on a Chip," Science, V. 261, August 13 (1993) 895-897.
CE	Dong-Woon Shin, Doo-Jin Choi. Geung-Ho Kim, "The Stacking Faults and Their Strain Effect at the Si/SiO ₂ Interfaces of a Directly Bonded SOI (silicon on insulator)," Thin Solid Films, V. 346, pp. 169-173, 1999.
CF	Q-Y. Tong, T-H Lee, and U. Gosele, "The Role of Surface Chemistry in Bonding of Standard Silicon Wafers," J. Electrochemical Society V. 144, N. 1, pp. 384-389, January 1997
CG	

EXAMINER:

DATE CONSIDERED:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.